



Three International Conferences in One Place

- **High Temperature Electronics (HiTEC)** •
- **Ceramic Interconnect & Ceramic Microsystems Tech. (CICMT)** •
- **Advanced Packaging for Power Electronics** •

A technology crossover event!

April 18-20, 2023 • Albuquerque, NM • Marriott Pyramid North

www.imaps.org



Three International Conferences in One Place

ONE EVENT, THREE INTERNATIONAL CONFERENCES, UNLIMITED OPPORTUNITIES

The forces behind the International Conferences on High Temperature Electronics (HiTEC), Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT), and Advanced Packaging for Power Electronics have joined for a special co-located technology extravaganza.

All three conferences will be held at the Marriott Pyramid North in Albuquerque, New Mexico from April 18-20, 2023. Each conference will sustain its own unique programming but share common networking and exhibitor functions.

KEY DATES AND LOCATION

Event Dates

April 18-20, 2023

Conference Programs	April 18-20
PDCs	April 17
Exhibition	April 18-19

Event Location & Hotel

Marriott Pyramid North
5151 San Francisco Road NE
Albuquerque, New Mexico USA

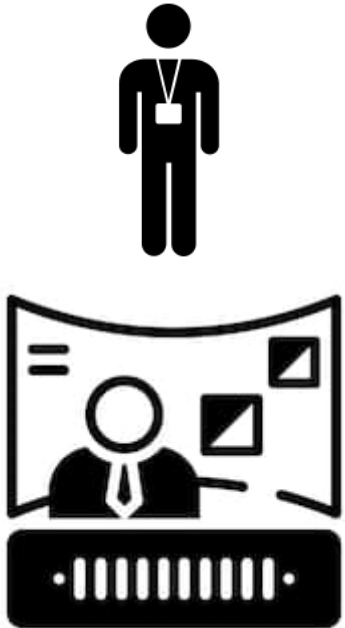


How to Book Your Room:

\$179/night + taxes and fees
Hotel block rates end on April 5th.

For online reservations, visit www.imaps.org
For reservations by phone call 1-888-236-2427.
Mention **IMAPS** when booking

HOW DOES IT WORK?



Come for one or come for all!

Each **attendee** registration includes joint access to all three conference programs, plus the networking and exhibit hall activities for one low price.

Each **exhibitor** registration includes a tabletop in the common networking hall and access to the common event registration list (3 times the reach of our traditional conferences!).

Sponsorship partners can choose from function sponsorships, single-conference sponsorships, or a premier multi-conference level of exposure. Each sponsorship includes a tabletop exhibit space in the common networking hall.

About the International Conference on High Temperature Electronics (HiTEC)

HiTEC 2023 continues the tradition of providing the leading biennial conference dedicated to the advancement and dissemination of knowledge of the high temperature electronics industry. Under the organizational sponsorship of the International Microelectronics Assembly and Packaging Society, HiTEC 2023 will be the forum for presenting leading high temperature electronics research results and application requirements. It will also be an opportunity to network with colleagues from around the world working to advance high temperature electronics. Abstracts and exhibitors will be accepted from, but not limited to, the following areas:

Applications:

- Geothermal
- Oil well logging
- Automotive
- Military/aerospace
- Space

Device Technologies:

- Si, SOI
- SiC
- Diamond
- GaN
- AlN
- Contacts
- Dielectrics

MEMS and Sensors:

- Vibration
- Pressure
- Seismic

Packaging:

- Materials
- Processing
- Solders/Brazes
- Substrates
- Wire Bonding
- Flip Chip
- Insulation
- Thermal management

Circuits:

- Analog
- Digital
- Power
- Wireless
- Mixed Signal

Energy Sources:

- Batteries
- Nuclear
- Fuel Cells

Passives:

- Resistors
- Inductors
- Capacitors
- Oscillators
- Connectors

Reliability & Modeling:

- AI Machine Learning
- Failure mechanisms
- Co-Design
- Prognostics & Health Management



About the 18th International Conference on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT)

The Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT) conference brings together a diverse set of disciplines to share experiences and promote opportunities to accelerate research, development and the application of ceramic interconnect and ceramic microsystems technologies. This international conference features ceramic technology for both microsystems and interconnect applications in the multi-session technical program. The committee is planning sessions and inviting speakers on the following topics:

1. Advanced materials for passive/active devices and their properties

- Microwave/mm-wave LTCC/ULTCC dielectric materials
- Ferroelectric/piezoelectric/pyroelectric/ferrite/multiferroic materials
- Sensitive ceramics/thermoelectric/electrocaloric materials
- Dielectric/ferroelectric/piezoelectric composites
- Pastes/inks/slurries for electronics

2. Material processing and device manufacturing technologies

- LTCC/HTCC and multilayer ceramic and glass processing
- Emerging ultralow temperature, room temperature processing, and cold sintering processing
- Additive manufacturing /3D printing/ direct writing
- Advanced thick film processing
- Thin Film Processing
- Fine structuring technologies
- Emerging embedding/integration technologies

3. Devices and Systems for emerging applications

- Circuits, antennas, and filters for MHz, GHz and THz for communications
- Automotive/aerospace/medical electronics/optoelectronics
- Flexible/wearable electronics
- Sensors and actuators (Integrated physical/chemical/biological)
- Packaging and integration issues for MEMS and BioMEMS devices
- Batteries/fuel cells/ energy conversion systems
- Micro-reactors/micro-fluidic devices

4. Design, modeling, simulation, characterization and reliability

- Metamaterials design, realization and characterization
- High frequency devices design/modeling/simulation
- Materials and devices characterization
- Material and device reliability, lifetime, and failure estimation
- Thermal management/thermal transfer simulation



About the International Conference on Advanced Packaging for Power Electronics

The Conference on Advanced Packaging for Power Electronics will bring together technologists from a diverse collection of disciplines in power semiconductor packaging, application development, reliability, modeling, process development, thermal management, and advanced materials/manufacturing to support the next generation of power electronics development. The committee is planning sessions and inviting speakers on the following topics:

POWER PACKAGING TECHNOLOGIES

- Advanced/Sustainable Materials
- Substrates & Module Designs
- Embedding Technologies
- Thermal Management
- Manufacturing Technologies
- Power Interposers
- Additive Manufacturing
- Attachment/Bonding/Joining Technologies
- Planar Interconnects
- Insulation Materials/Strategies

APPLICATIONS

- Board Mount Power
- Granular Power
- Data Center Power
- Embedded Components
- Integrated Capacitors & Magnetics
- Energy Storage
- Automotive Electronics
- EV Charging
- Power Flip Chip
- Distributed Energy Interfaces

TOOLS

- Multiphysics Modeling
- Co-Design Simulation
- Characterization Techniques
- Physics of Failure Analysis
- Roadmapping
- Reliability



PREMIER SPONSOR

EVENT SPONSOR FOR

Conference reception
-and-
Conference lunches (two days)

RECOGNITION

IMAPS.org sitewide footer ad
from March-April 2023

Full page ad in conference final
program

Recognition signage
throughout crossover areas

Leading logo exposure across
all three conference webpages,
marketing emails, final
programs, and all applicable
outlets

EXTRA BENEFITS

Double tabletop exhibit space

Two (2) complimentary full
event registrations & 2 exhibit
personnel registrations

Additional Discounted full
event registrations (\$500)

Collateral distribution on site
(provided by sponsor)

\$6,000

Max 3 available

HiTEC SPONSOR

EVENT SPONSOR FOR

Conference breakfasts and
Tuesday breaks (co-
sponsorship)

RECOGNITION

Final program half page ad

Recognition signage in/near
HiTEC conference room

Logo exposure on the HiTEC
webpage, marketing emails,
final program, and all
applicable outlets

EXTRA BENEFITS

One tabletop exhibit space in
joint networking hall

One (1) complimentary full
event registration & 1 exhibit
personnel registration

Additional Discounted full
event registrations (\$500)

\$3,000

Max 4 available

CICMT SPONSOR

EVENT SPONSOR FOR

Conference breakfasts and
Tuesday breaks (co-
sponsorship)

RECOGNITION

Final program half page ad

Recognition signage in CICMT
conference room

Logo exposure on the CICMT
webpage, marketing emails,
final program, and all
applicable outlets

EXTRA BENEFITS

One tabletop exhibit space in
joint networking hall

One (1) complimentary full
event registration & 1 exhibit
personnel registration

Additional Discounted full
event registrations (\$500)

\$3,000

Max 4 available

POWER SPONSOR

EVENT SPONSOR FOR

Conference breakfasts and
Tuesday breaks (co-
sponsorship)

RECOGNITION

Final program half page ad

Recognition signage in Power
conference room

Logo exposure on the Power
webpage, marketing emails,
final program, and all
applicable outlets

EXTRA BENEFITS

One tabletop exhibit space in
joint networking hall

One (1) complimentary full
event registration & 1 exhibit
personnel registration

Additional Discounted full
event registrations (\$500)

\$3,000

Max 4 available



HiTEC · CICMT · Power

Sponsorship and Exhibit Opportunities

COFFEE BREAK SPONSOR

EVENT SPONSOR FOR

One networking coffee break
(Wed or Thurs –
co-sponsorships possible)

RECOGNITION

Recognition signage during the
coffee break

Logo exposure on the
conference webpages,
marketing emails, final
program, and all outlets

BENEFITS

Discounted full event
registrations (\$500)

\$1,500

Max 6 available

TABLETOP EXHIBITOR

INCLUDES

One six-foot table with two
chairs and access to electricity

One badge – full QR booth

PDF attendee list

RECOGNITION

Exhibitor listing in program

BENEFITS

Discounted full event
registrations (\$500), booth
personnel (\$150)

\$900-\$1,150

Max 30 available

HOW TO COMMIT TO A TABLETOP | Early Registration Discounts End March 24th

Exhibitor Details

Only 30 exhibitor spaces are available! These WILL sell out, so book early!

Exhibitor Fees	Member	Non-Member
Early Registration <i>Booked on or before March 24th</i>	\$900	\$1000
Regular Registration <i>Booked after March 24th</i>	\$1050	\$1150

How to Register as an Exhibitor

1. Register for a tabletop space or sponsorship online via the conference websites (www.imaps.org).
2. Log into an existing account. New to IMAPS? Create a visitor profile to complete registration.
3. Select the tabletop exhibition option on the registration page.
4. Complete payment.
5. IMAPS staff will instructions months prior to the show for shipping details, badge details, and more.

HOW TO COMMIT TO A SPONSORSHIP

- Premier Sponsor**
\$6,000
- HiTEC Sponsor**
\$3,000
- CICMT Sponsor**
\$3,000
- Power Packaging Sponsor**
\$3,000
- Coffee Break Sponsor**
\$1,500

1. Register online for your sponsorship option or contact Brian Schieman, Executive Director, at bschieman@imaps.org with your sponsorship selection and questions.
2. You will provide payment in full online or can request an invoice and payment instructions.
3. Email your high-resolution logo file and URL to link to upon commitment to sponsor.
4. Program Ads are due to IMAPS by March 31st.
5. IMAPS staff will contact you several weeks prior to the show to confirm shipping details, request badge details, and more.

Don't see what you want? All sponsorships can be customized to match your event exposure goals.



HiTEC · CICMT · Power Packaging

www.imaps.org

Contact Us

www.imaps.org

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info@imaps.org

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